
RX62N Group, RX621 Group

Asynchronous SCIA Transmission/Reception Using the DMA Controller (DMACA)

R01AN0266EJ0100
Rev.1.00
Feb 14, 2011

Introduction

This application note presents a sample program that performs SCI (serial communications interface) asynchronous serial communication using the Renesas MCU's DMA controller (DMAC).

Target Devices

The RX62N Group and RX621 Group products

Other members of the RX Family that have the same I/O registers (peripheral unit control registers) as the RX62N Group and RX621 Group products can also use the code from this application note. Note, however, that since certain aspects of the functions used may be changed in other devices due to function additions or other differences, the documentation for the device used must be checked carefully before using this code. When using this code in an end product or other application, its operation must be tested and evaluated thoroughly.

Contents

1. Specifications	2
2. Operation Confirmation Environment.....	2
3. Functions Used	3
4. Operation.....	3
5. Software	7
6. Reference Documents.....	15

1. Specifications

The code presented in this application note performs serial communication (transmission and reception) by performing data transfers between RAM and the SCI (serial communications interface) module using the DMA controller (DMAC). Figure 1 presents an overview of this asynchronous serial data transmission and reception that uses the DMAC.

1. This program uses the SCI module's channel 2 and the DMAC module's channels 0 (reception) and 1 (transmission).
2. An 8-bit length, one stop bit, no parity bit communication format is used.
3. For the transmit operation, the DMAC is activated by the transmit data empty interrupt request, and it transfers the transmit data, which is prepared in advance from an arbitrary transfer source to the SCI transmit data register (TDR).
4. For the receive operation, the DMAC is activated by the receive data full interrupt request, and it transfers the receive data from the SCI receive data register (RDR) to an arbitrary transfer destination that is prepared in advance.
5. When the specified number of transfers have been performed, these operations are reinitialized.

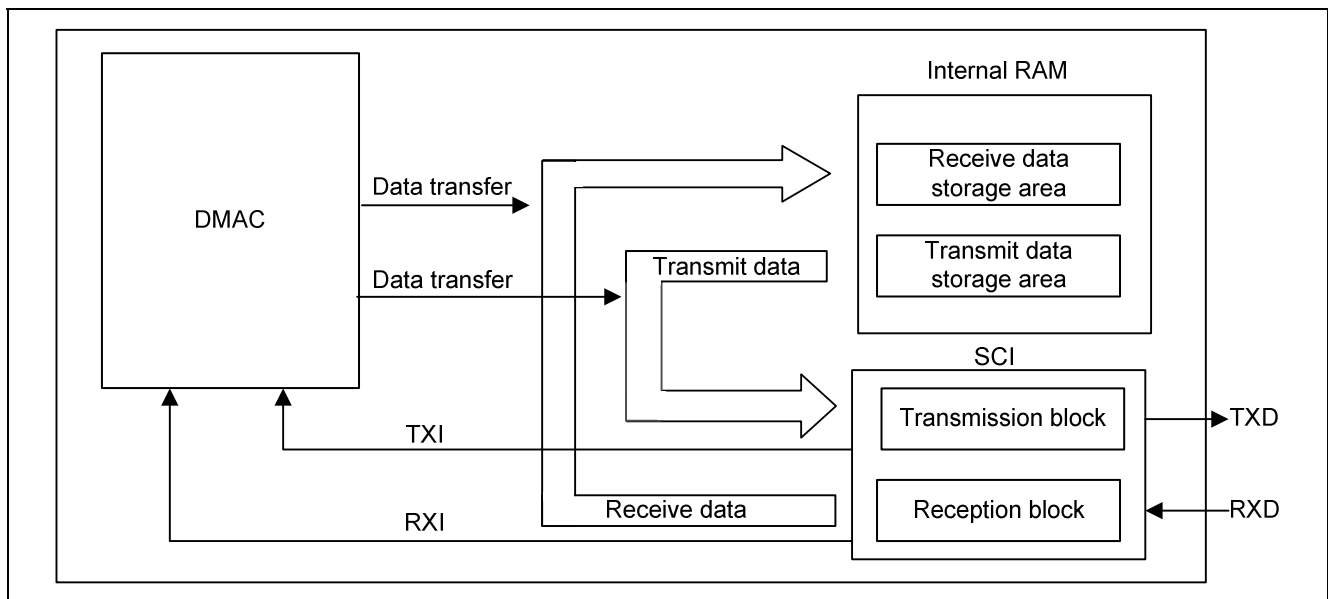


Figure 1 Overview of Asynchronous Serial Data Transmission/Reception Using the DMAC

2. Operation Confirmation Environment

Table 1 lists the environment required for confirming master operation.

Table 1 Operation Confirmation Environment

Item	Description
Device	RX62N (R5F562N8BDBG)
Board	Renesas Starter Kit (R0K5562N0S000BE)
Power supply voltage	5.0 V (CPU operating voltage: 3.3 V)
Input clock	12 MHz (ICLK = 96 MHz, PCLK = 48 MHz, BCLK = 24 MHz)
Operating temperature	Room temperature
HEW	Version 4.07.00.007
Toolchain	RX Standard Toolchain (V.1.0.0.0)
Debugger/emulator	E20 emulator
Debugger component	RX E1/E20 SYSTEM V.1.00.00.000

3. Functions Used

- Clock generation circuit
- Low power consumption functions
- Interrupt control unit (ICU)
- Serial communication interface (SCI)
- DMA controller (DMAC)

See the RX62N Group, RX621 Group User’s Manual: Hardware for detailed information.

4. Operation

4.1 Operation Mode Settings

In the sample program, mode pins are set to MD1 = 1, MD0 = 1 to select single-chip mode as the operating mode, the ROME bit in system control register 0 (SYSCR0) is set to 1 to enable the on-chip ROM, and the EXBE bit in the SYSCR0 register is cleared to 0 to disable the external bus.

Table 2 lists the operating mode settings used in the sample program.

Table 2 Operating Mode Settings

Mode Pin		SYSCR0 Register		Operating Mode	On-Chip ROM	External Bus
MD1	MD0	ROME	EXBE			
1	1	1	0	Single-chip mode	Enabled	Disabled

Note: The initial settings of the ROME and EXBE bits in the SYSCR0 register are SYSCR0.ROME = 1 and SYSCR0.EXBE = 0, so it is not necessary for the sample program to make settings to the SYSCR0 register.

4.2 Clock Settings

The evaluation board used for this application note includes a 12.0 MHz crystal oscillator.

Therefore this application note uses the following settings for the system clock (ICLK), the peripheral module clock (PCLK), and the external bus clock (BCLK): 8× (96 MHz), 4× (48 MHz), and 2× (24 MHz).

4.3 Endian Mode Setting

The sample program presented in this application note supports both big- and little-endian mode. Table 3 lists the hardware endian mode settings of the master device.

Table 3 Endian Mode Settings (Hardware)

MDE pin	Endian
0	Little endian
1	Big endian

Table 4 lists the endian settings used in the compiler options.

Table 4 Endian Mode Settings (Compiler Options)

MCU Option	Endian
endian = little	Little endian
endian = big	Big endian

Note: Set the MDE pin to match the endian mode selected as a compiler option.

4.4 Bit Order Settings

The program in this application note supports both right and left as the bit order. Table 5 lists the bit order settings in the microcontroller option in the compiler options.

Table 5 Bit Order Settings (Compiler Options)

MCU Option	Bit Order
bit_order = right	Bit field members are allocated in order starting with the low-order bit. (Default)
bit_order = left	Bit field members are allocated in order starting with the high-order bit.

- Notes:
1. In this application note, bit fields are used in the I/O register definitions file (iodefine.h). In the I/O register definitions file, "left" is specified with the #pragma bit_order extension, and the bit field members are allocated in order starting with the high-order bit.
 2. If both the bit_order compiler option and the #pragma bit_order extension are specified, the #pragma bit_order extension specification takes precedence. Thus the bit fields defined in the I/O register definitions file will be allocated in order starting with the high-order bit, regardless of the compiler options bit_order specification.

4.5 SCI Settings

Table 6 lists the SCI communication function settings used in this sample program.

Table 6 SCI Settings and Conditions

Channel Used	SCI 2
Communication mode	Asynchronous serial communication mode
Interrupts	<ul style="list-style-type: none"> • Receive error interrupt (ERI) • Receive data full interrupt (RXI) • Transmit data empty interrupt (TXI) • Transmit complete interrupt (TEI)
Communication speed	38,400 bps (PCLK = 48 MHz)
Data length	8-bit data
Stop bits	1 stop bit
Parity	None

4.6 DMAC Settings

Table 7 lists the DMAC transfer conditions used in this sample program.

Table 7 DMAC Transfer Conditions

Condition	SCI Transmit DMAC Transfer Conditions (TXI2)	SCI Receive DMAC Transfer Conditions (RXI2)
Channel used	Channel 1 (DMAC1)	Channel 0 (DMAC0)
Transfer mode	Normal transfer mode	Normal transfer mode
Transfer count	256	256
Transfer data	Size: byte Data content: 256 bytes with values from H'00 to H'FF	Size: byte Data content: An arbitrary 256 bytes of data
Transfer source	Internal RAM	Receive data register (SCI2.RDR)
Transfer destination	Transmit data register (SCI2.TDR)	Internal RAM
Transfer source address	The transfer source address is incremented after the transfer	The transfer source is fixed
Transfer destination address	The transfer destination is fixed	The transfer destination address is incremented after the transfer
Start event	Started on the SCI transmit data empty interrupt	Started on the SCI receive data full interrupt
Interrupts	An interrupt is issued to the CPU after the specified data transfer completes.	An interrupt is issued to the CPU after the specified data transfer completes.

4.7 Operation Timing

Figure 2 shows the timing of the operations performed by this sample program.

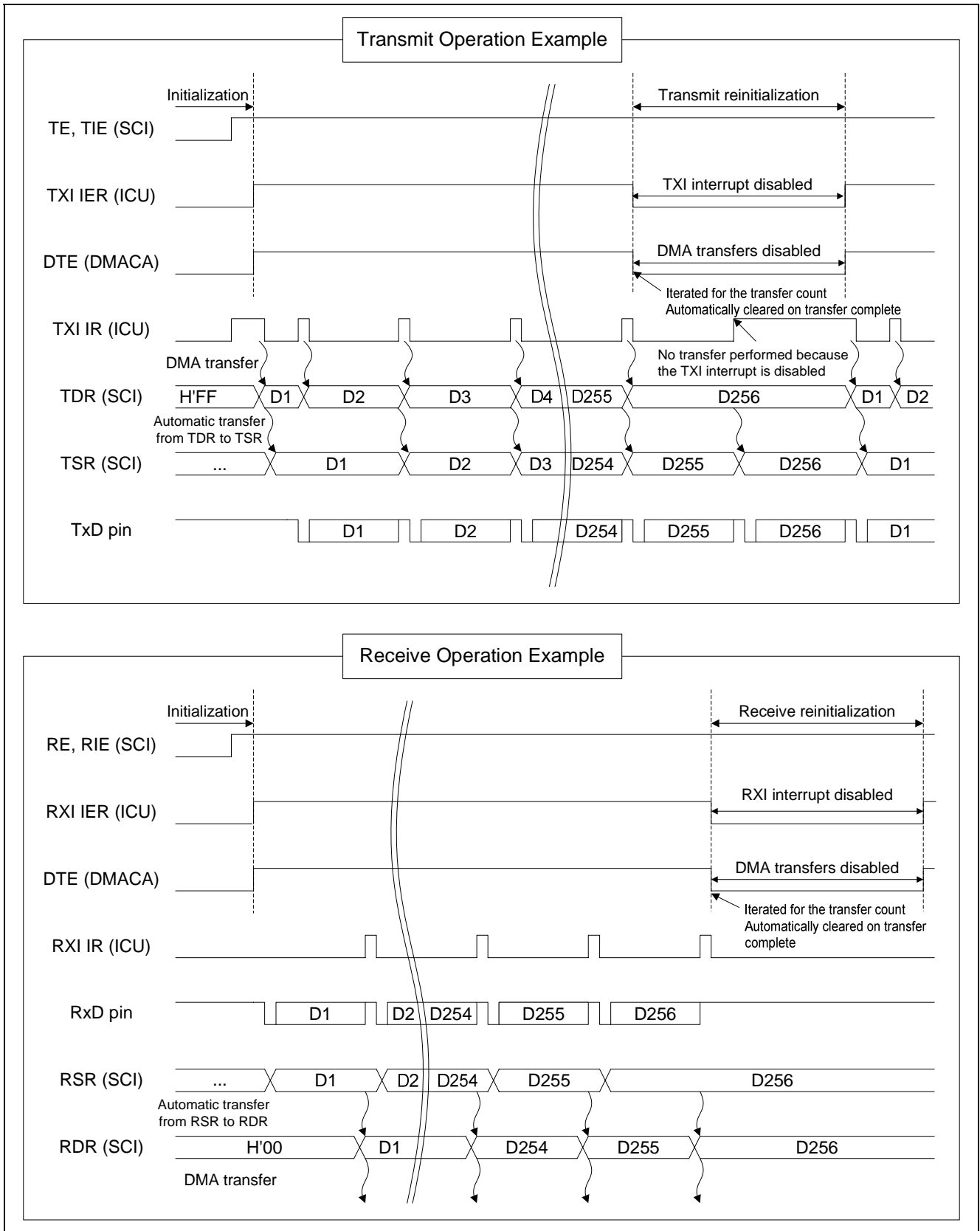


Figure 2 Operation Timing

Note: Note that when the DMAC is used for a reception operation in the RX62N Group and RX621 Group microcontrollers, if the next transfer request occurs before the IR flag is cleared automatically, the transfer request will be lost. See section 11.7, Usage Notes, in the RX62N Group and RX621 Group User's Manual - Hardware for details.

5. Software

5.1 Constants

Table 8 lists the constants used in the sample code.

Table 8 Constants

Constant Name	Set Value	Usage
DMAC_CNT	256	DMAC transfer count
BUF_SIZE	256	Buffer size

5.2 Variables

Table 9 lists the variables used in the sample program.

Table 9 Variables

Type	Variable	Usage	Functions
unsigned char	recvBuff[BUF_SIZE]	Array variable that holds the serial receive data	main, dmac1_init, int_sci_tei2
unsigned char	trnsBuff[BUF_SIZE]	Array variable that holds the serial transmit data	dmac0_init, DMAC0_dmtend_int

5.3 Functions

Table 10 lists the functions used in this application note's sample program.

Table 10 Functions

Function Name	Operation
HardwareSetup	Initialization, clock settings, and clearing the module stop state
main	Main processing ICUa initialization and setting the interrupt levels
dmac0_init	DMAC0 initialization
dmac1_init	DMAC1 initialization
sci2_init	SCI initialization and setting the transfer clock
DMAC0_dmtend_int	DMAC0 transfer complete interrupt
DMAC1_dmtend_int	DMAC1 transfer complete interrupt
int_sci_tei2	Transmit complete interrupt
int_sci_eri2	Receive error interrupt

5.4 Processing Flow

Figures 3 to 11 show the processing flow of the sample program.

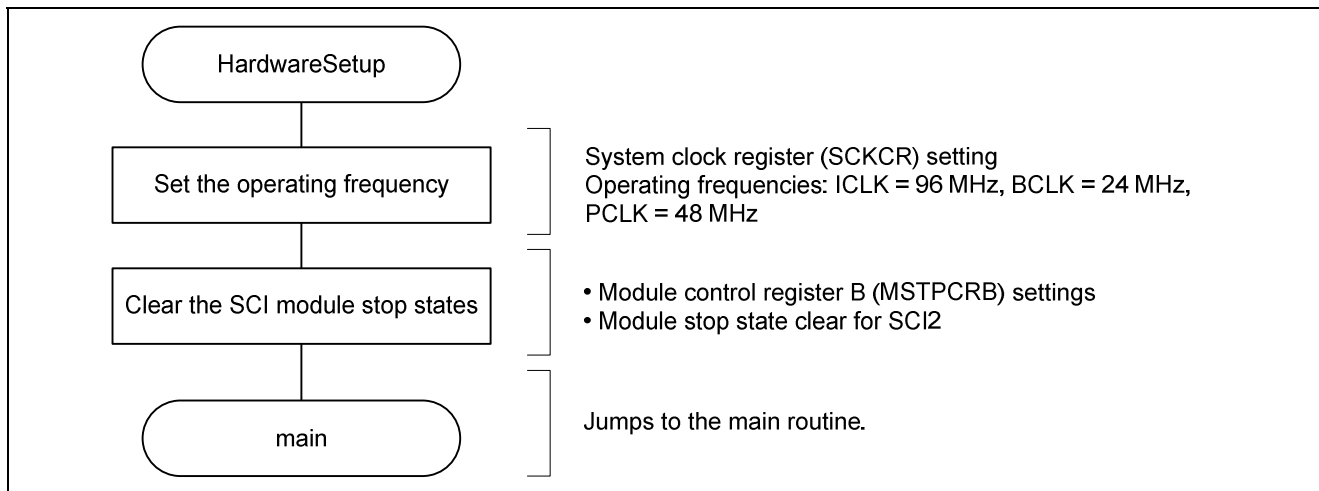


Figure 3 Initialization Processing

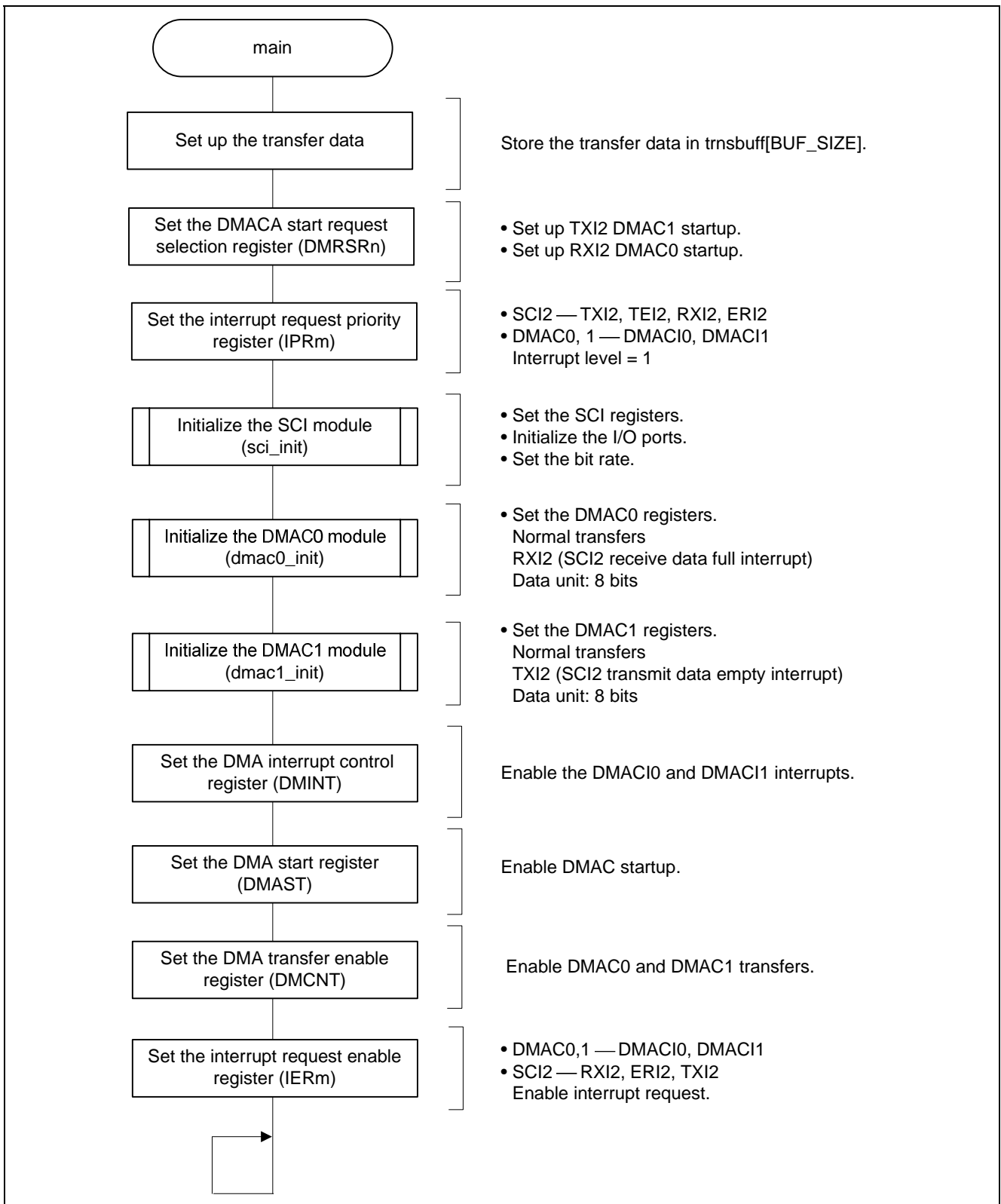


Figure 4 Main Processing

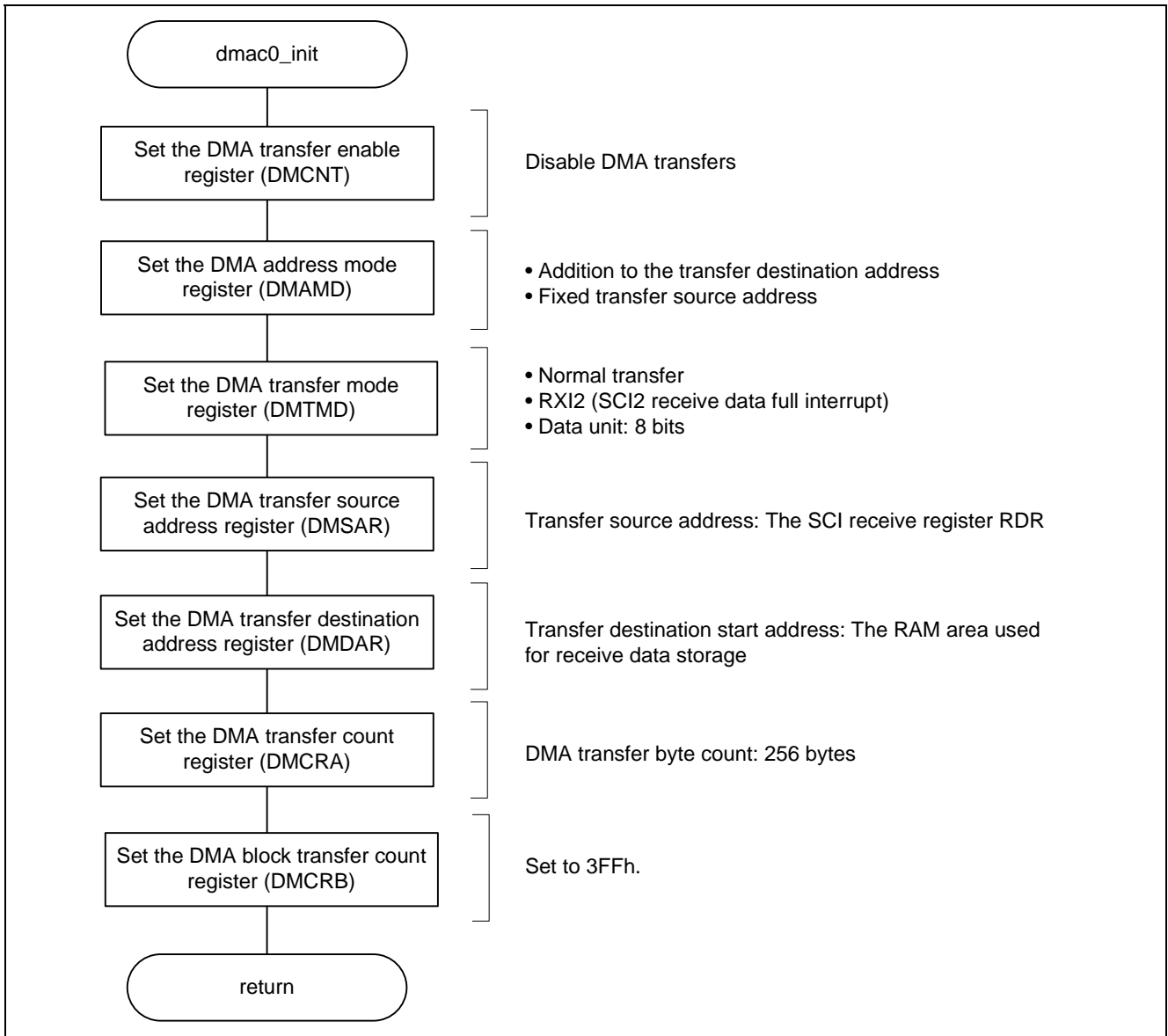


Figure 5 DMAC0 Initialization

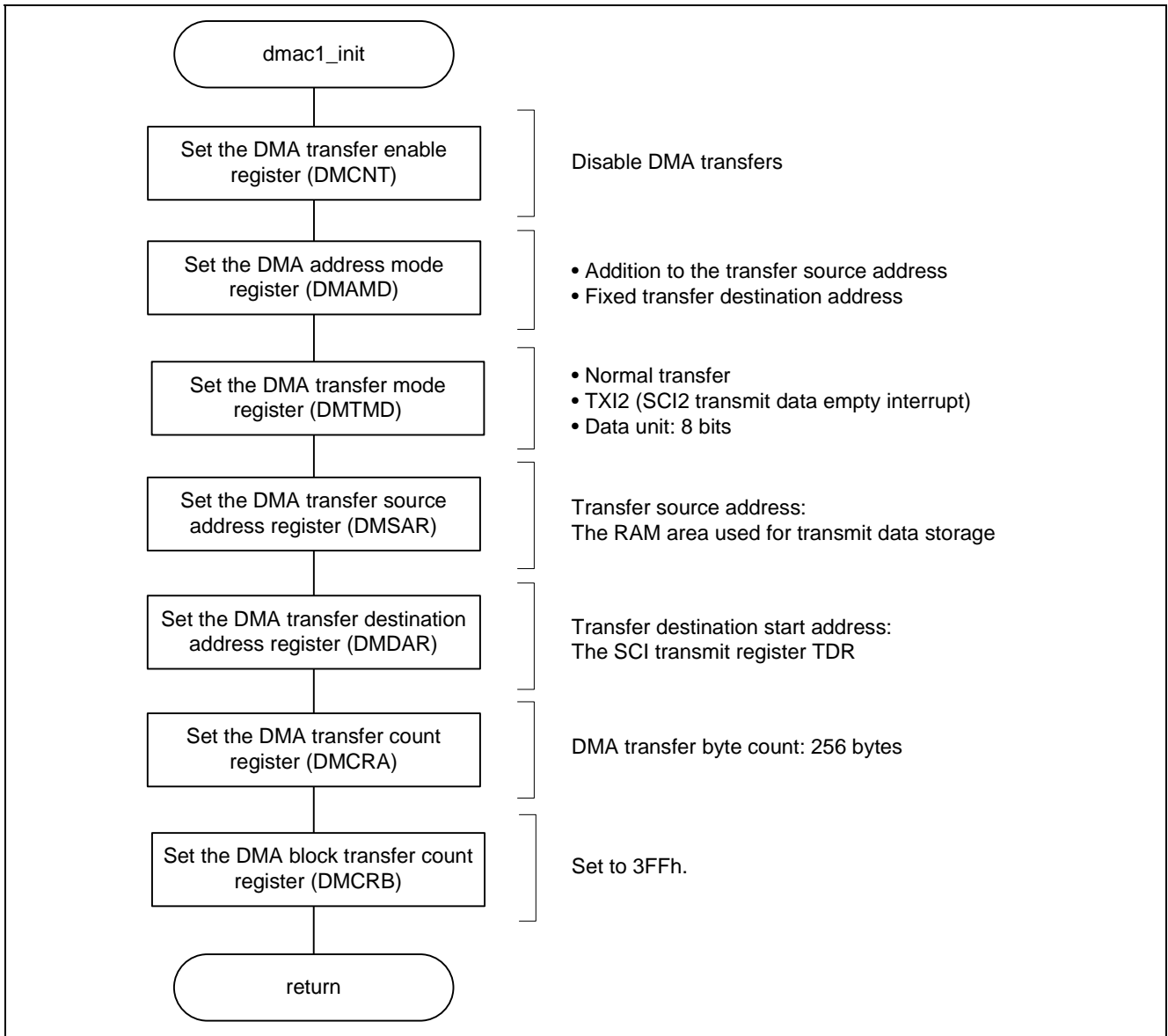


Figure 6 DMAC1 Initialization

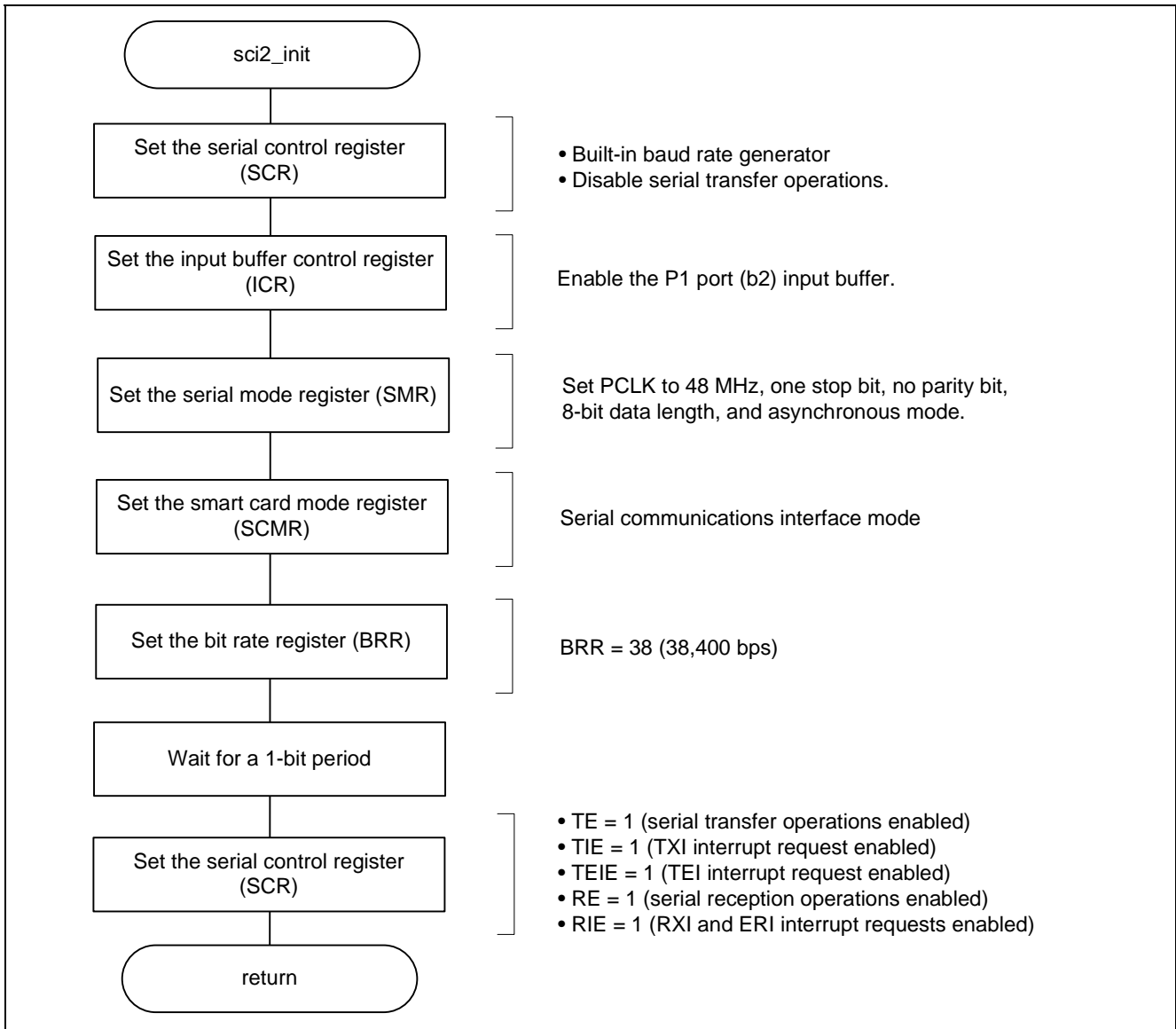


Figure 7 SCI Initialization

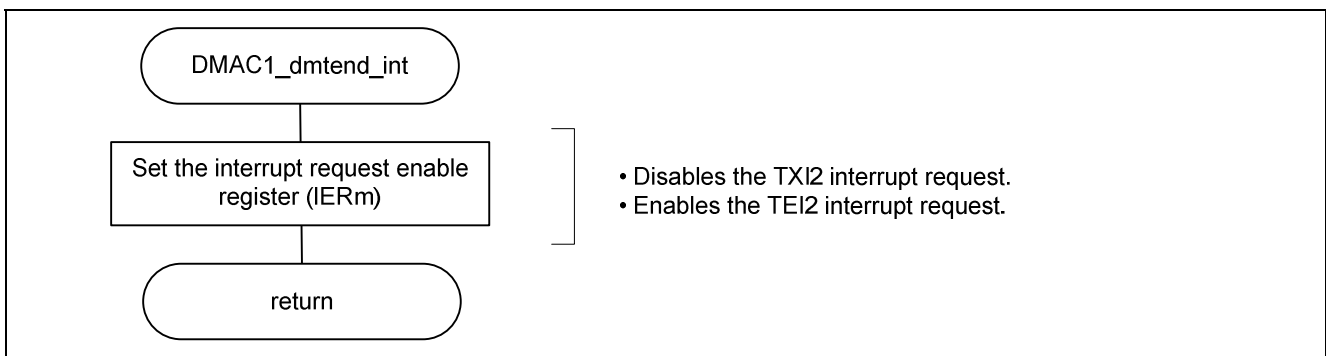


Figure 8 DMAC1 Transfer Complete Interrupt

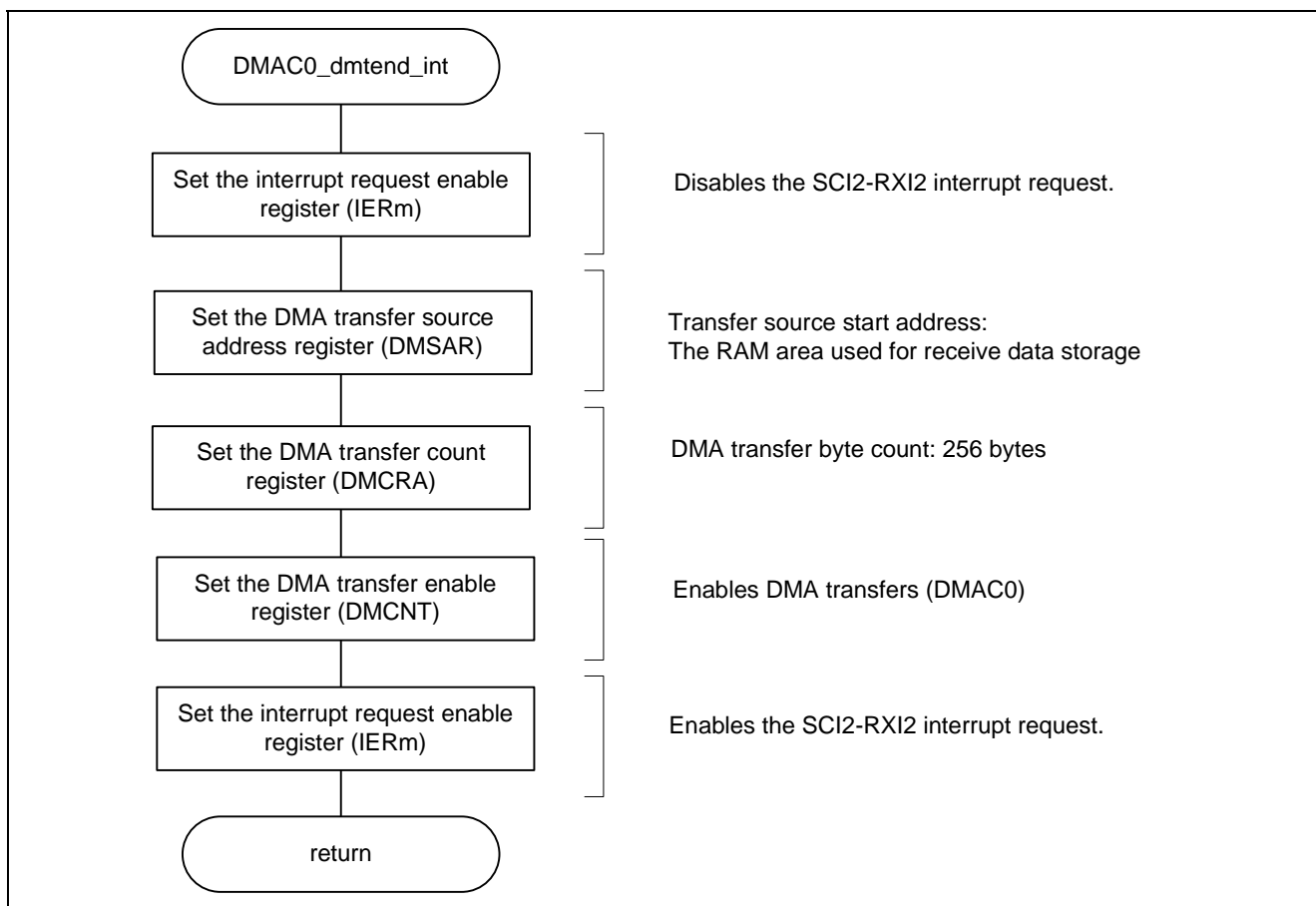


Figure 9 DMAC0 Transfer Complete Interrupt

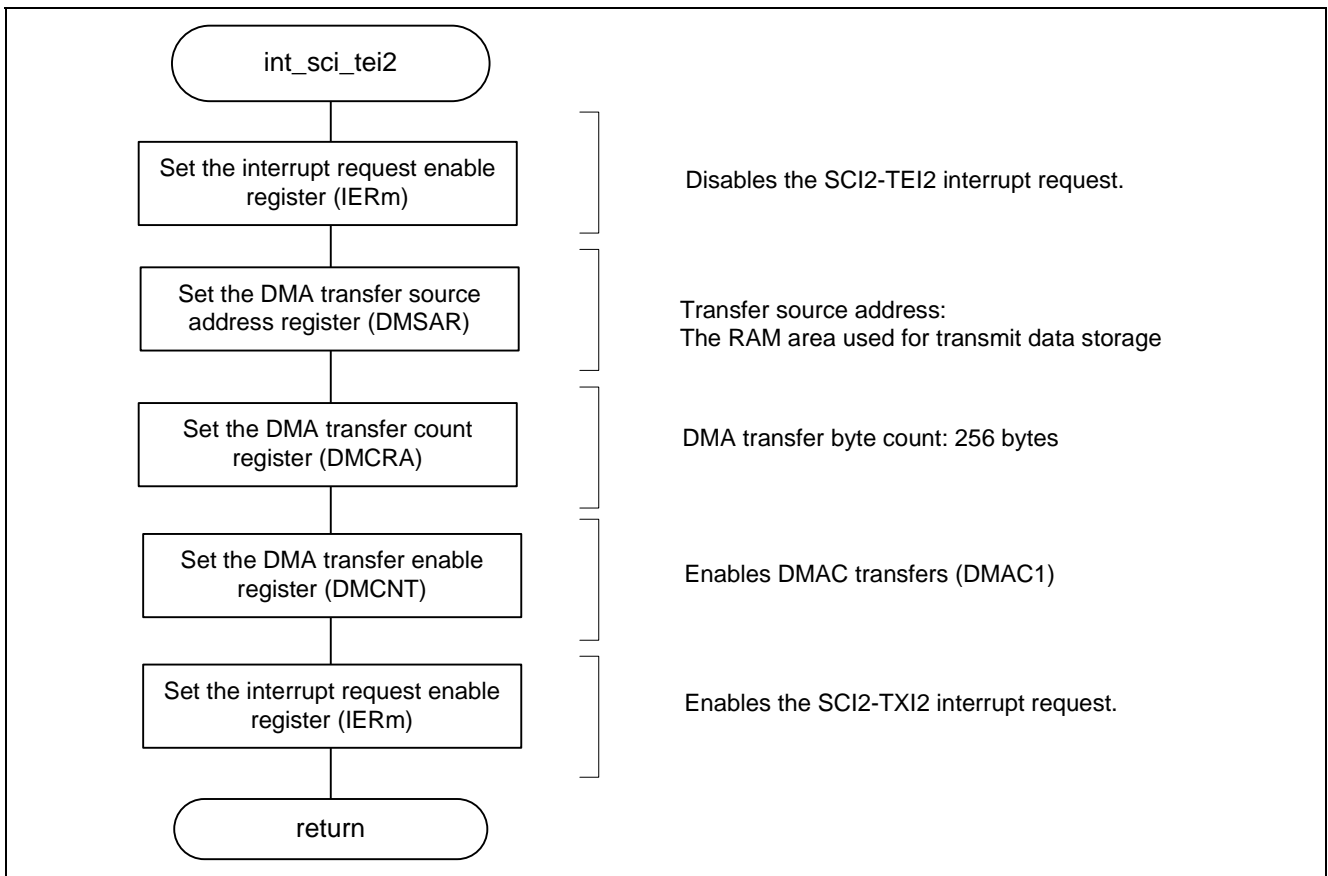


Figure 10 Transmit Complete Interrupt

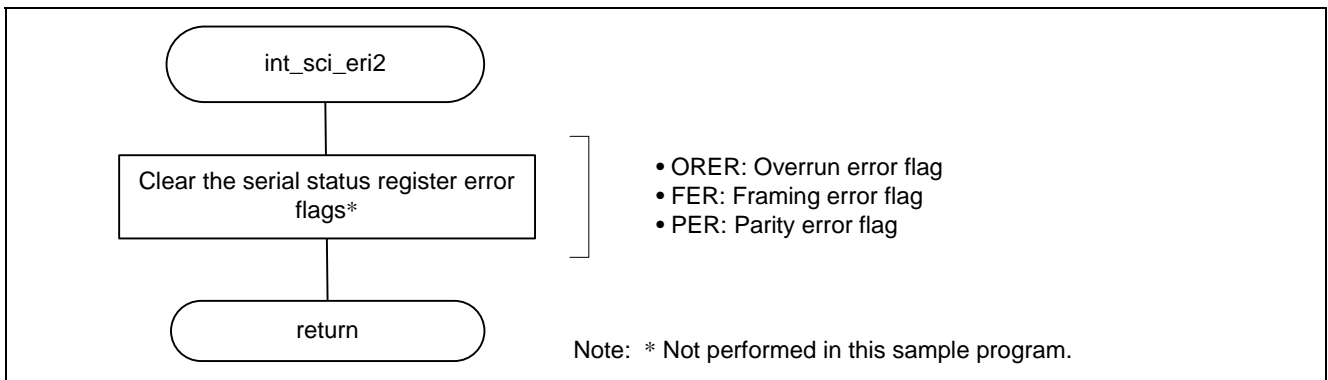


Figure 11 Receive Error Interrupt

6. Reference Documents

- Hardware Manual
RX62N Group, RX621 Group User's Manual: Hardware
(The latest version can be downloaded from the Renesas Electronics Web site.)
- Software Manual
RX Family User's Manual: Software
(The latest version can be downloaded from the Renesas Electronics Web site.)
- Development Environment Manual
RX Family C/C++ Compiler Package User's Manual
(The latest version can be downloaded from the Renesas Electronics Web site.)
- Technical Updates
(The latest information can be downloaded from the Renesas Electronics Web site.)

Website and Support

Renesas Electronics Website

<http://www.renesas.com/>

Inquiries

<http://www.renesas.com/inquiry>

All trademarks and registered trademarks are the property of their respective owners.

Revision Record

Rev.	Date	Description	
		Page	Summary
1.00	Feb.14.11	—	First edition issued

General Precautions in the Handling of MPU/MCU Products

The following usage notes are applicable to all MPU/MCU products from Renesas. For detailed usage notes on the products covered by this document, refer to the relevant sections of the document as well as any technical updates that have been issued for the products.

1. Handling of Unused Pins

Handle unused pins in accord with the directions given under Handling of Unused Pins in the manual.

- The input pins of CMOS products are generally in the high-impedance state. In operation with an unused pin in the open-circuit state, extra electromagnetic noise is induced in the vicinity of LSI, an associated shoot-through current flows internally, and malfunctions occur due to the false recognition of the pin state as an input signal become possible. Unused pins should be handled as described under Handling of Unused Pins in the manual.

2. Processing at Power-on

The state of the product is undefined at the moment when power is supplied.

- The states of internal circuits in the LSI are indeterminate and the states of register settings and pins are undefined at the moment when power is supplied.

In a finished product where the reset signal is applied to the external reset pin, the states of pins are not guaranteed from the moment when power is supplied until the reset process is completed. In a similar way, the states of pins in a product that is reset by an on-chip power-on reset function are not guaranteed from the moment when power is supplied until the power reaches the level at which resetting has been specified.

3. Prohibition of Access to Reserved Addresses

Access to reserved addresses is prohibited.

- The reserved addresses are provided for the possible future expansion of functions. Do not access these addresses; the correct operation of LSI is not guaranteed if they are accessed.

4. Clock Signals

After applying a reset, only release the reset line after the operating clock signal has become stable. When switching the clock signal during program execution, wait until the target clock signal has stabilized.

- When the clock signal is generated with an external resonator (or from an external oscillator) during a reset, ensure that the reset line is only released after full stabilization of the clock signal. Moreover, when switching to a clock signal produced with an external resonator (or by an external oscillator) while program execution is in progress, wait until the target clock signal is stable.

5. Differences between Products

Before changing from one product to another, i.e. to a product with a different part number, confirm that the change will not lead to problems.

- The characteristics of an MPU or MCU in the same group but having a different part number may differ in terms of the internal memory capacity, layout pattern, and other factors, which can affect the ranges of electrical characteristics, such as characteristic values, operating margins, immunity to noise, and amount of radiated noise. When changing to a product with a different part number, implement a system-evaluation test for the given product.

Notice

1. All information included in this document is current as of the date this document is issued. Such information, however, is subject to change without any prior notice. Before purchasing or using any Renesas Electronics products listed herein, please confirm the latest product information with a Renesas Electronics sales office. Also, please pay regular and careful attention to additional and different information to be disclosed by Renesas Electronics such as that disclosed through our website.
2. Renesas Electronics does not assume any liability for infringement of patents, copyrights, or other intellectual property rights of third parties by or arising from the use of Renesas Electronics products or technical information described in this document. No license, express, implied or otherwise, is granted hereby under any patents, copyrights or other intellectual property rights of Renesas Electronics or others.
3. You should not alter, modify, copy, or otherwise misappropriate any Renesas Electronics product, whether in whole or in part.
4. Descriptions of circuits, software and other related information in this document are provided only to illustrate the operation of semiconductor products and application examples. You are fully responsible for the incorporation of these circuits, software, and information in the design of your equipment. Renesas Electronics assumes no responsibility for any losses incurred by you or third parties arising from the use of these circuits, software, or information.
5. When exporting the products or technology described in this document, you should comply with the applicable export control laws and regulations and follow the procedures required by such laws and regulations. You should not use Renesas Electronics products or the technology described in this document for any purpose relating to military applications or use by the military, including but not limited to the development of weapons of mass destruction. Renesas Electronics products and technology may not be used for or incorporated into any products or systems whose manufacture, use, or sale is prohibited under any applicable domestic or foreign laws or regulations.
6. Renesas Electronics has used reasonable care in preparing the information included in this document, but Renesas Electronics does not warrant that such information is error free. Renesas Electronics assumes no liability whatsoever for any damages incurred by you resulting from errors in or omissions from the information included herein.
7. Renesas Electronics products are classified according to the following three quality grades: "Standard", "High Quality", and "Specific". The recommended applications for each Renesas Electronics product depends on the product's quality grade, as indicated below. You must check the quality grade of each Renesas Electronics product before using it in a particular application. You may not use any Renesas Electronics product for any application categorized as "Specific" without the prior written consent of Renesas Electronics. Further, you may not use any Renesas Electronics product for any application for which it is not intended without the prior written consent of Renesas Electronics. Renesas Electronics shall not be in any way liable for any damages or losses incurred by you or third parties arising from the use of any Renesas Electronics product for an application categorized as "Specific" or for which the product is not intended where you have failed to obtain the prior written consent of Renesas Electronics. The quality grade of each Renesas Electronics product is "Standard" unless otherwise expressly specified in a Renesas Electronics data sheets or data books, etc.
"Standard": Computers; office equipment; communications equipment; test and measurement equipment; audio and visual equipment; home electronic appliances; machine tools; personal electronic equipment; and industrial robots.
"High Quality": Transportation equipment (automobiles, trains, ships, etc.); traffic control systems; anti-disaster systems; anti-crime systems; safety equipment; and medical equipment not specifically designed for life support.
"Specific": Aircraft; aerospace equipment; submersible repeaters; nuclear reactor control systems; medical equipment or systems for life support (e.g. artificial life support devices or systems), surgical implantations, or healthcare intervention (e.g. excision, etc.), and any other applications or purposes that pose a direct threat to human life.
8. You should use the Renesas Electronics products described in this document within the range specified by Renesas Electronics, especially with respect to the maximum rating, operating supply voltage range, movement power voltage range, heat radiation characteristics, installation and other product characteristics. Renesas Electronics shall have no liability for malfunctions or damages arising out of the use of Renesas Electronics products beyond such specified ranges.
9. Although Renesas Electronics endeavors to improve the quality and reliability of its products, semiconductor products have specific characteristics such as the occurrence of failure at a certain rate and malfunctions under certain use conditions. Further, Renesas Electronics products are not subject to radiation resistance design. Please be sure to implement safety measures to guard them against the possibility of physical injury, and injury or damage caused by fire in the event of the failure of a Renesas Electronics product, such as safety design for hardware and software including but not limited to redundancy, fire control and malfunction prevention, appropriate treatment for aging degradation or any other appropriate measures. Because the evaluation of microcomputer software alone is very difficult, please evaluate the safety of the final products or system manufactured by you.
10. Please contact a Renesas Electronics sales office for details as to environmental matters such as the environmental compatibility of each Renesas Electronics product. Please use Renesas Electronics products in compliance with all applicable laws and regulations that regulate the inclusion or use of controlled substances, including without limitation, the EU RoHS Directive. Renesas Electronics assumes no liability for damages or losses occurring as a result of your noncompliance with applicable laws and regulations.
11. This document may not be reproduced or duplicated, in any form, in whole or in part, without prior written consent of Renesas Electronics.
12. Please contact a Renesas Electronics sales office if you have any questions regarding the information contained in this document or Renesas Electronics products, or if you have any other inquiries.

(Note 1) "Renesas Electronics" as used in this document means Renesas Electronics Corporation and also includes its majority-owned subsidiaries.

(Note 2) "Renesas Electronics product(s)" means any product developed or manufactured by or for Renesas Electronics.



SALES OFFICES

Renesas Electronics Corporation

<http://www.renesas.com>

Refer to "<http://www.renesas.com/>" for the latest and detailed information.

Renesas Electronics America Inc.

2880 Scott Boulevard Santa Clara, CA 95050-2554, U.S.A.
Tel: +1-408-588-6000, Fax: +1-408-588-6130

Renesas Electronics Canada Limited

1101 Nicholson Road, Newmarket, Ontario L3Y 9C3, Canada
Tel: +1-905-898-5441, Fax: +1-905-898-3220

Renesas Electronics Europe Limited

Dukes Meadow, Millboard Road, Bourne End, Buckinghamshire, SL8 5FH, U.K
Tel: +44-1628-585-100, Fax: +44-1628-585-900

Renesas Electronics Europe GmbH

Arcadiastrasse 10, 40472 Düsseldorf, Germany
Tel: +49-211-65030, Fax: +49-211-6503-1327

Renesas Electronics (China) Co., Ltd.

7th Floor, Quantum Plaza, No.27 ZhiChunLu Haidian District, Beijing 100083, P.R.China
Tel: +86-10-8235-1155, Fax: +86-10-8235-7679

Renesas Electronics (Shanghai) Co., Ltd.

Unit 204, 205, AZIA Center, No.1233 Lujiazui Ring Rd., Pudong District, Shanghai 200120, China
Tel: +86-21-5877-1818, Fax: +86-21-6887-7858 / -7898

Renesas Electronics Hong Kong Limited

Unit 1601-1613, 16/F., Tower 2, Grand Century Place, 193 Prince Edward Road West, Mongkok, Kowloon, Hong Kong
Tel: +852-2886-9318, Fax: +852 2886-9022/9044

Renesas Electronics Taiwan Co., Ltd.

7F, No. 363 Fu Shing North Road Taipei, Taiwan
Tel: +886-2-8175-9600, Fax: +886 2-8175-9670

Renesas Electronics Singapore Pte. Ltd.

1 HarbourFront Avenue, #06-10, Keppel Bay Tower, Singapore 098632
Tel: +65-6213-0200, Fax: +65-6278-8001

Renesas Electronics Malaysia Sdn.Bhd.

Unit 906, Block B, Menara Amcorp, Amcorp Trade Centre, No. 18, Jln Persiaran Barat, 46050 Petaling Jaya, Selangor Darul Ehsan, Malaysia
Tel: +60-3-7955-9390, Fax: +60-3-7955-9510

Renesas Electronics Korea Co., Ltd.

11F., Samik Lavied' or Bldg., 720-2 Yeoksam-Dong, Kangnam-Ku, Seoul 135-080, Korea
Tel: +82-2-558-3737, Fax: +82-2-558-5141